

Application Data Sheet

Application Information

Application Type:: Regular
Subject Matter:: Utility
Title:: Method And Structure To Reduce
Risk Of Gold Embrittlement In Solder
Joints
Attorney Docket Number:: TI-36327 (1962-08300)
Request for Early Publication?:: No
Request for Non-Publication?:: No
Suggested Drawing Figure:: 1
Total Drawing Sheets:: 2
Small Entity?:: No

Applicant Information

Applicant Authority type:: Inventor
Primary Citizenship Country:: P.R. China
Status:: Full Capacity
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Representative Information

Representative Customer Number:: 23494

Assignee Information

Assignee name:: Texas Instruments Incorporated
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